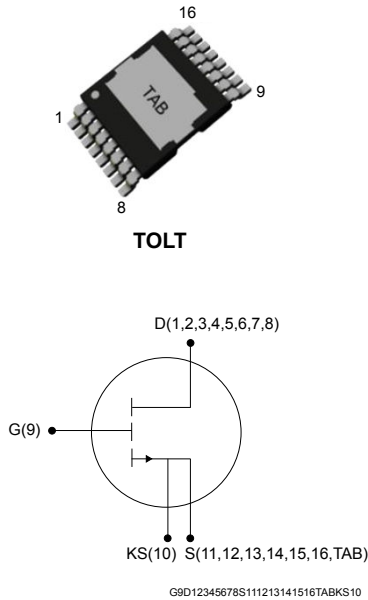


## 700 V, 18 mΩ typ., e-mode PowerGaN transistor



### Product status link

[SGT023R70FTP](#)

### Product summary

Order code	SGT023R70FTP
Marking	023R70F
Package	TOLT
Packing	Tape and reel

### Features

Order code	$V_{DS}$	$R_{DS(on)}$ max.	$I_D$	Series
SGT023R70FTP	700 V	23 mΩ	TBD <sup>(1)</sup>	G-HEMT

1. TBD stands for "to be defined".

- Enhancement mode normally off transistor
- Very high switching speed
- High power management capability
- Extremely low capacitances
- Zero reverse recovery charge
- ESD safeguard

### Applications

- Industrial
- Motor drive
- Totem and datacenter SMPS

### Description

The **SGT023R70FTP** is a 700 V, e-mode PowerGaN transistor. The resulting device provides extremely low conduction losses, high current capability and ultra-fast switching operation to enable high power density and unbeatable efficiency performances.

## 1 Electrical ratings

$T_C = 25\text{ °C}$  unless otherwise specified.

**Table 1. Absolute maximum ratings**

Symbol	Parameter	Value	Unit
$V_{DS}$	Drain-source voltage	700 <sup>(1)</sup>	V
	Drain-source voltage (transient, $t_p < 200\text{ }\mu\text{s}$ )	800	
$V_{GS}$	Gate-source voltage	-6 to 7	V
$I_D$	Drain current (continuous)	TBD	A
$I_{DM}$	Pulse drain current ( $t_p = 20\text{ }\mu\text{s}$ )	TBD	A
$P_{TOT}$	Total power dissipation at $T_C = 25\text{ °C}$	480	W
$T_{stg}$	Storage temperature range	-55 to 150	°C
$T_J$	Operating junction temperature range		°C

1. Recommended continuous maximum bus voltage during switching operations should not exceed 450 V.

**Table 2. Thermal data**

Symbol	Parameter	Value	Unit
$R_{thJC}$	Thermal resistance, junction-to-case	0.26	°C/W
$R_{thJA}$	Thermal resistance, junction-to-ambient	48.36 <sup>(1)</sup>	°C/W

1. When mounted on a standard 1 inch<sup>2</sup> area of FR-4 PCB with 2-oz copper.

## 2 Electrical characteristics

$T_C = 25\text{ °C}$  unless otherwise specified.

**Table 3. Static**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$I_{DSS}$	Drain-source leakage current	$V_{GS} = 0\text{ V}, V_{DS} = 700\text{ V}$		10	380	$\mu\text{A}$
		$V_{GS} = 0\text{ V}, V_{DS} = 700\text{ V}, T_J = 125\text{ °C}$		113		
$I_{GSS}$	Gate-source leakage current	$V_{DS} = 0\text{ V}, V_{GS} = 6\text{ V}$		284		$\mu\text{A}$
$V_{GS(th)}$	Gate threshold voltage	$V_{DS} = V_{GS}, I_D = 94.8\text{ mA}$	1.2	1.7	2.5	V
$R_{DS(on)}$	Static drain-source on-resistance	$V_{GS} = 6\text{ V}, I_D = 2.5\text{ A}$		18	23	$\text{m}\Omega$
		$V_{GS} = 6\text{ V}, I_D = 26\text{ A}, T_J = 125\text{ °C}$		36		

**Table 4. Dynamic**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$C_{iss}$	Input capacitance	$V_{GS} = 0\text{ V}, V_{DS} = 400\text{ V}, f = 100\text{ kHz}$	-	818	-	pF
$C_{oss}$	Output capacitance		-	233	-	pF
$C_{rss}$	Reverse transfer capacitance		-	2.2	-	pF
$C_{o(er)}^{(1)}$	Equivalent output capacitance energy related	$V_{GS} = 0\text{ V}, V_{DS} = 0\text{ to }400\text{ V}$	-	329	-	pF
$C_{o(tr)}^{(2)}$	Equivalent output capacitance time related		-	474	-	pF
$R_g$	Intrinsic gate resistance	$f = 5\text{ MHz}, I_D = 0\text{ A}$	-	2.8	-	$\Omega$
$V_{plat}$	Gate plateau voltage	$V_{DS} = 400\text{ V}, I_D = 26\text{ A}$	-	2.1	-	V
$Q_g$	Total gate charge	$V_{GS} = 0\text{ to }6\text{ V}, V_{DS} = 400\text{ V}, I_D = 26\text{ A}$	-	18.2	-	nC
$Q_{gs}$	Gate-source charge		-	1.7	-	nC
$Q_{gd}$	Gate-drain charge		-	5.7	-	nC
$Q_{rr}$	Reverse recovery charge	$V_{GS} = 0\text{ V}, V_{DS} = 400\text{ V}$	-	0	-	nC
$Q_{oss}$	Output charge		-	190	-	nC

- $C_{o(er)}$  is a constant capacitance value that gives the same stored energy as  $C_{oss}$  while  $V_{DS}$  is rising from 0 to the stated value.
- $C_{o(tr)}$  is a constant capacitance value that gives the same charging time as  $C_{oss}$  while  $V_{DS}$  is rising from 0 to the stated value.

**Table 5. Reverse conduction**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$V_{SD}$	Source-drain reverse voltage	$V_{GS} = 0\text{ V}, I_{SD} = 26\text{ A}$	-	2.3	-	V

## Revision history

**Table 6. Document revision history**

Date	Revision	Changes
03-Oct-2025	1	First release.

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